7SL-XR7620

Intel® 4/5th XEON® Scalable, 2U, 2-socket Short-depth Military Rugged

- Two Intel® 4th /5th Xeon® Scalable Processor CPUs with up to 32 Cores
- 16 DDR5 DIMM slots, supports RDIMM 1 TB max, speeds up to 5600 MT/s. Supports registered ECC DDR5 DIMMs only
- Front bays: Up to 4 x 2.5-inch SATA III, SAS, or NVMe SSDs max 61.44 TB, up to 8 x E3.S NVMe direct drives, 51.2TB max
- Cryptographically signed firmware, Secure Boot, TPM 2.0 FIPS, CC-TCG certified
- 2 x 10G LAN,1x RJ45 1GbE LAN ,1 x USB 3.0, 1 x USB2.0,1 x Mini-DP
- Up to 5 PCIe slots (4 x16 Gen4/Gen5, 1 x 16 LP Gen4)
- Redundant 1800W Platinum power supply support 100V-240V, 240V HVDC support 1+1 active-active support hot plug
- Embedded Management: iDRAG Direct, iDRAC RESTful API with Redfish iDRAC Service
- Lightweight aluminum chassis with stainless steel reinforcement
- Electrical interference input filtering and cable shielding
- Conformal coating (Options)
- Design to meet MIL-STD-461/MIL-STD-810

Product Highlight

Technical Specification

- 5th/4th Gen Intel® Xeon® Scalable processors, Two Socket LGA-4677 (Socket E)
- Up to 16/32 Cores per Processor
- Up to 1TB memory with 16 DIMM slots
- Storage Internal Controllers: PERC H965i, PERC H965e, PERC H755, PERC H355, HBA355i
- (BOSS-N1): HWRAID 1, 2 x M.2 NVMe SSDs

Management and Operating System

- Windows®, VMWARE, Ubuntu Server LTS, Windows Server with Hyper-V, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, VMware ESX
- AMI UEFI BIOS type
- iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, NativeEdge Endpoint Orchestrator
- TPM 2.0 support

Expansion

- Up to 5 PCIe slots (4 x16 Gen4/Gen5, 1 x 16 LP Gen4)
- 4x 2.5-inch SATA III, SAS, or NVMe SSDs max 61.44 TB, Up to 8 x E3.S NVMe direct drives, 51.2TB max

Input/Output Versatility

- 1 x Power Button
- 1 x SSD Status LED
- 2 x AC-IN Jack (Front)
- 1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0 (Rear)
- 1 x iDRAC dedicated port, 1 x USB 3.0, 1 x Serial (Micro- AB USB 2.0) port, 1 x Mini-DisplayPort, 1 x RJ45 for dry contact, 2 x 10 GbE

Power Supply Options

- Redundant 1800 W Platinum 100/240V VAC
- 1100 W 48 V~ (60) VDC (Optional)

Thermal Solution

Air Cooling 6 x Standard cold swap fans

Environmental

Operating

- Temperature: -10°C to 55°C
- Humidity: 5%to 95%, non-condensing
- Shock: 3 axis, 25g
- Vibration: 5Grms

Non-Operating

- Temperature: -20°C to 60°C
- Humidity: 5%to 95%, non-condensing

Mechanical

- Height: 3.41 inches (86.8mm)
- Width: 19 inches (482.6mm)
- Depth: 22 inches (572mm) with bezel
- 18.57inches (471.8mm) without bezel
- Weight: 46.64 pounds (21.16 kg)

Specifications

System

Processor	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
CPU Core Count	Up to 16 Cores/32 Cores
Memory type	DDR5-5600MT/s RDIMM ECC, up to 1TB in 8 DIMM slot
GPU Options	Up to 5 x 75W (Single Width Full Height/Half Length, Low Profile) GPU or Up to 2 x 300W (Double Width Full Height/Full Length)
TPM	Chipset: Infineon, Type: TPM 2.0
IPMI	iDRAC RESTful API with Redfish
BIOS	AMI UEFI BIOS
USB	1x USB3.0 +1x USB2.0 ports
Ethernet	4x 25G Ethernet SFP+ Ports
Power Type	100V~240V AC IN Redundant
Storage	4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drives
Operating Temp.	-10℃ to +55℃
Dimension	482mm(W) x 572mm(D)x86mm(H)

Front I/O

Power Button	1x
SSD LED indicator	1x
Swappable SSD Tray	4x
iDRAC	1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0

Rear I/O

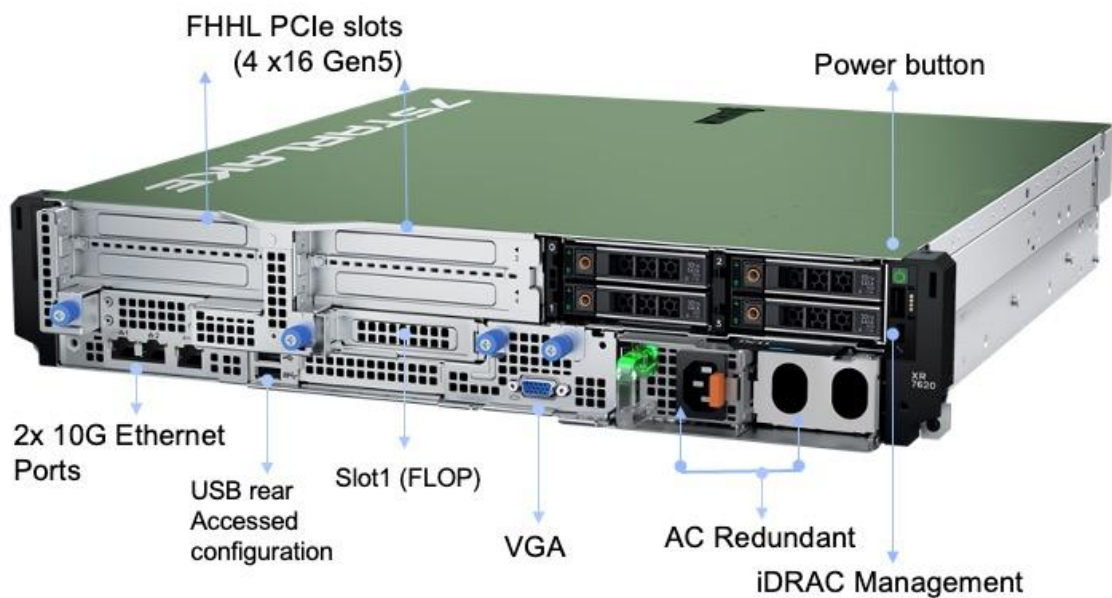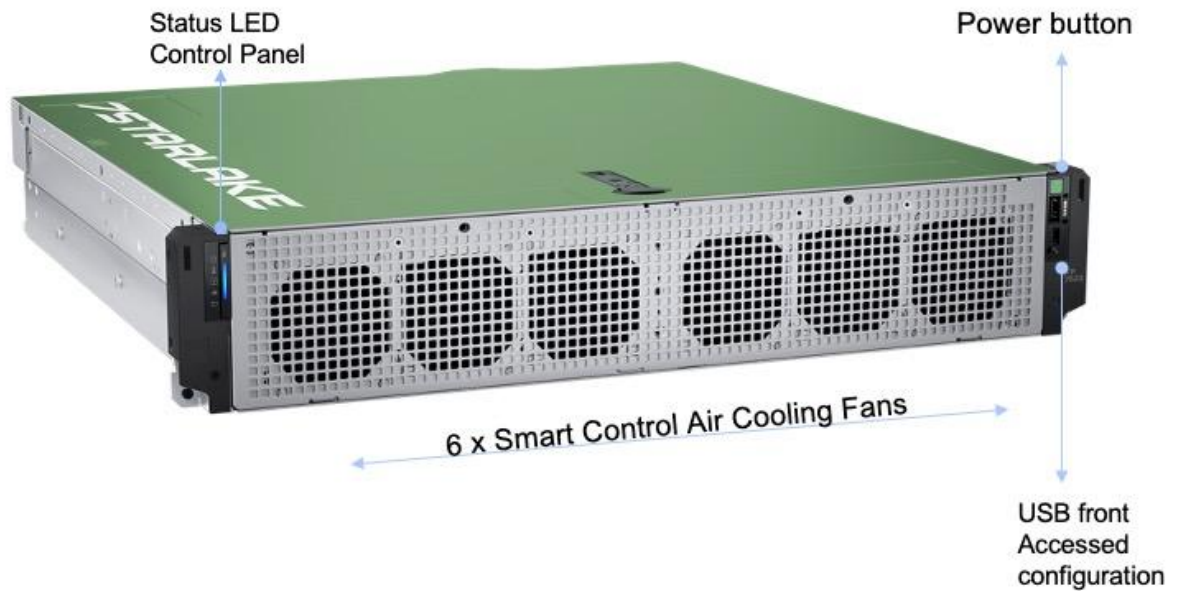|	
iDRAC	1x iDRAC dedicated Direct port
USB3.0	1x
Serial	1 x (Micro-AB USB 2.0)
1G LAN	1x
10 LAN	2x
Display port	1x Mini-DP or VGA

Environmental

MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating) Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)
Operating Temp	-10℃ to +55℃
Storage Temp.	-20℃ to +60℃
Relative Humidity	5% to 95%, non-condensing.

Ordering Information

	7SL-XR7620-AC	7SL-XR7620-DC
CPU	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)	Two 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
RAM	DDR5-5600MT/s RDIMM ECC, up to 1TB in 16 DIMM slot	DDR5-5600MT/s RDIMM ECC, up to 1TB in 16 DIMM slot
Storage	4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drive	4x 2.5" Swappable SATA SAS, or NVMe SSD or 8 x E3.S NVMe direct drive
Power	1800W 100V~240V AC IN Redundant	1100W DC 48V~60V
Thermal	Active Smart Fan Cooling	Active Smart Fan Cooling

Appearance

Status LED Control Panel

Power button

6 x Smart Control Air Cooling Fans

USB front Accessed configuration

FHHL PCIe slots (4 x16 Gen5)

Power button

2x 10G Ethernet Ports

USB rear Accessed configuration

Slot1 (FLOP)

VGA

AC Redundant

iDRAC Management